

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT2837022

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
JUNG-SOO JUNG	04/30/2014
HYUN-JEONG KANG	04/30/2014
YOUNG-BIN CHANG	04/30/2014
SUK-WON KIM	04/30/2014
SANG-KYU BAEK	04/30/2014
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<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	443-742
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	14266555
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<b>NAME OF SUBMITTER:</b>	WILLIAM A. MUNCK
<b>SIGNATURE:</b>	/William A. Munck/
<b>DATE SIGNED:</b>	04/30/2014
<b>Total Attachments: 2</b>	
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PATENT



ASSIGNMENT

WHEREAS, We, **Jung-Soo Jung**, resident of Seongnam-si, Gyeonggi-do, Republic of Korea, citizen of Republic of Korea, **Hyun-Jeong Kang**, resident of Gangnam-gu, Seoul, Republic of Korea, citizen of Republic of Korea, **Young-Bin Chang**, resident of Anyang-si, Gyeonggi-do, Republic of Korea, citizen of Republic of Korea, **Suk-Won Kim**, resident of Yongin-si, Gyeonggi-do, Republic of Korea, citizen of Republic of Korea, and **Sang-Kyu Baek**, resident of Suwon-si, Gyeonggi-do, Republic of Korea, citizen of Republic of Korea, have invented certain new and useful improvements in a "METHOD AND APPARATUS FOR PROVIDING OPTIMAL TRANSMISSION AND RECEPTION BEAMS IN BEAMFORMING SYSTEM" disclosed in an application for United States Letters Patent (Application Serial No. \_\_\_\_/\_\_\_\_\_, filed on \_\_\_\_\_, said application having been executed concurrently herewith;

WHEREAS, SAMSUNG ELECTRONICS CO., LTD, a corporation organized under the laws of the Republic of Korea, having a place of business at 129, Samsung-ro, Yeongtong-gu, Suwon-si, Gyeonggi-do, 443-742, Republic of Korea (hereinafter referred to as "ASSIGNEE"), is desirous of acquiring our entire right, title and interest in and to the invention, and in and to the said application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, the full and exclusive right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, continuations-in-part and extensions thereof; We authorize William A. Munck of Munck Wilson Mandala, LLP to insert in the parenthesis above the application number and filing date of said application when known; and we hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patents resulting therefrom, insofar as our interest is concerned, to the said ASSIGNEE of our entire right, title and interest.

We also hereby sell and assign to said ASSIGNEE, its successors, assigns and legal representatives the full and exclusive rights, title and interest to the invention disclosed in said application throughout the world, including the right to file applications and obtain patents, utility models, industrial models and designs for said invention in its own name throughout the world including all rights of priority, all rights to publish cautionary notices reserving ownership of said invention and all rights to register said invention in appropriate registries; and we further agree to execute any and all powers of attorney, applications, assignments, declarations, affidavits, and any other papers in connection therewith necessary to perfect such rights, title and interest in ASSIGNEE, its successors, assigns and legal representatives.

We hereby further agree that we will communicate to said ASSIGNEE, or to its successors, assigns and legal representatives, any facts known to us respecting any improvements; and, at the expense of said ASSIGNEE, to testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, continuation-in-part, reissue and substitute applications, and make all lawful oaths, and generally do everything possible to vest title in said ASSIGNEE and to aid said ASSIGNEE, its successors, assigns and legal representatives to obtain and enforce proper protection for said invention in all countries.

Date: April 30, 2014

  
Jung-Soo JUNG

Date: April 30, 2014

  
Hyun-Jeong KANG

Date: April 30, 2014

  
Young-Bin Chang

Date: April 30, 2014

  
Suk-Won Kim

Date: April 30, 2014

  
Sang-Kyu BAEK